Z21: Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

Z22: These assemblies are ESD sensitive, ESD precautions shall be observed.

Z23: These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

Z24: These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE

<table>
<thead>
<tr>
<th>LAYER NAME</th>
<th>BOARD #: TIDA-01427</th>
<th>REV: E2</th>
<th>SUN REV: Not In VersionControl</th>
</tr>
</thead>
<tbody>
<tr>
<td>M6 Assembly Bottom</td>
<td>TID #: TIDA-01427</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
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